

ABSTRACT OF THE DISCLOSURE

To provide a method of manufacturing an electronic part capable of reusing the remaining conductive particles and electrically connecting the electronic part to the counterpart substrate, a method of manufacturing an electronic part includes: forming a mask on an active surface of the wafer on which electrode pads of the electronic part are formed, the mask of a predetermined height having openings provided above the electrode pads, forming bumps inside of the openings of the mask provided above the electrode pads, the bumps having a height lower than that of the mask, scattering conductive particles above the active surface of the wafer, removing the conductive particles remaining on the surface of the mask, fixing the conductive particles on the surfaces of the bumps, removing the mask, and separating the electronic part from the wafer.